

What is claimed is:

1. A semiconductor device with a plurality of semiconductor chips stacked on a substrate, wherein said semiconductor device comprising;

5 a wiring layer disposed so as to be sandwiched between said semiconductor chips, and

a plurality of bonding pads, for connecting a bonding wire, provided on said wiring layer, thereto.

2. A semiconductor device according to claim 1, wherein
10 a connection wiring for connecting among said bonding pads is provided in said wiring layer.

3. A semiconductor device according to claim 1, wherein
said plurality of bonding pads are disposed so as to surround
a semiconductor chip stacked on an upper surface of said
15 wiring layer.

4. A semiconductor device according to claim 1, wherein
a via hole is provided in said wiring layer, said via hole
is connected to a bonding pad of a semiconductor chip disposed
below said wiring layer.

20 5. A semiconductor device with a plurality of semiconductor chips stacked on a substrate, wherein said semiconductor device comprising;

a wiring layer disposed so as to be sandwiched between said semiconductor chips,

25 a plurality of bonding pads, for connecting a bonding wire, provided on said wiring layer, thereto and

a connection wiring for connecting said bonding pads provided in said wiring layer.

6. A semiconductor device with a plurality of

semiconductor chips stacked on a substrate, wherein said semiconductor device comprising;

a wiring layer disposed so as to be sandwiched between said semiconductor chips,

5 a plurality of bonding pads, for connecting a bonding wire, provided on said wiring layer, thereto,

a connection wiring for connecting among said bonding pads provided in said wiring layer, and

10 a via hole, connected to said bonding pad of a semiconductor chip disposed below said wiring layer, and provided on said wiring layer.